

D E C L A R A T I O N

As a below named inventor(s), I (we) hereby declare that:

My (our) residence, post office address and citizenship are as stated below next to my (our) name;

I (we) believe I (we) am (are) the original, first and sole inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **BONDPAD ATTACHMENTS USED TO TEMPORARILY CONNECT SEMICONDUCTOR DIE**; the specification of which is attached hereto;

I (we) hereby state that I (we) have reviewed and understand the contents of the above identified specification, including the claims;

I (we) acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations Section 1.56(a);

I (we) hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign applications(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed;

I (we) hereby claim the benefit under Title 35, United States Code Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I (we) acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application;

I (we) hereby declare that all statements made of my (our) own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon;

POWER OF ATTORNEY: As a named inventor, I appoint the following as attorney(s)/agent(s) to transact all business in the Patent and Trademark Office for this application; David J. Paul, (Registration #34,692), Michael W. Starkweather, (Registration #34,441), Stanley N. Protigal, (Registration #28,657), Angus C. Fox, III, (Registration #31,828), Susan B. Collier, (Registration #34,566) Lia M. Pappas, (Registration #34,095), William R. Bachand, (Registration #34,980), and/or Ozer M. N. Teitelbaum (Registration #36,698).

Send Correspondence to: Stanley N. Protigal, Patent Attorney
Micron Semiconductor, Inc.
2805 East Columbia Road
Boise, Idaho 83706
Telephone: 208-368-4508

100
Inventor's Full Name: Warren M. Farnworth
(First) (MI) (Last)

Inventor's Signature: Warren M Farnworth Date: 6-7-93

Citizenship: United States of America

Post Office Address: 2004 S. Banner

Nampa, Idaho 83686-7271 ID

City, State and
Country of Residence Nampa, Idaho United States of America ID

200
Inventor's Full Name: Alan G. Wood
(First) (MI) (Last)

Inventor's Signature: Alan G. Wood Date: 6/4/93

Citizenship: United States of America

Post Office Address: 1366 E. Versailles Court

Boise, Idaho 83706 ID

City, State and
Country of Residence Boise, Idaho United States of America ID

<u>Trung</u> (First)	<u>T</u> (MI)	<u>Doan</u> (Last)
-------------------------	------------------	-----------------------

James J. Van Date: 6/3/93

United States of America

1574 Shenandoah Drive

Boise, Idaho 83712-6668

Boise, Idaho United States of America ID

David R. Hembree
(First) (MI) (Last)

David M. Mahan Date: 6-4-93

United States of America

10855 Smoke Ranch Drive

Boise, Idaho 83709-1259

Boise, Idaho United States of America ID